

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/06/2022

Details for "TLC2654AC-8D"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLC2654AC-8D	NIPDAU	Level-1-260C-UNLIM	TI TAIWAN A/T	D 8	3.91x4.9x1.58	85.3

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000001	0.001108	11	0.000001	0
Precious Metals	Gold	7440-57-5	0.090254	99.997784	999978	0.105798	1058
Precious Metals	Silver	7440-22-4	0.000001	0.001108	11	0.000001	0
Sub-Total			0.090256	100	1000000	0.1058	1058
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.706063	79.999977	800000	0.827662	8277
Thermoplastics	Epoxy	85954-11-6	0.176516	20.000023	200000	0.206916	2069
Sub-Total			0.882579	100	1000000	1.034578	10346
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	24.25509	97.41	974100	28.43234	284323
Copper and Its Alloys	Iron	7439-89-6	0.5976	2.4	24000	0.70052	7005
Copper and Its Alloys	Phosphorus	7723-14-0	0.00747	0.03	300	0.008756	88
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00747	0.03	300	0.008756	88
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.00747	0.03	300	0.008756	88
Zinc and Its Alloys	Zinc	7440-66-6	0.0249	0.1	1000	0.029188	292
Sub-Total			24.9	100	1000000	29.188318	291883
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.355273	95.119946	951199	0.416459	4165
Precious Metals	Gold	7440-57-5	0.002913	0.77992	7799	0.003415	34
Precious Metals	Palladium	7440-05-3	0.015314	4.100134	41001	0.017951	180
Sub-Total			0.3735	100	1000000	0.437825	4378
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	49.435282	88	880000	57.949105	579491
Other Plastics and Rubber	Carbon Black	1333-86-4	0.168529	0.299999	3000	0.197553	1976
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.308971	0.550001	5500	0.362182	3622
Thermoplastics	Epoxy	85954-11-6	6.263675	11.15	111500	7.342415	73424
Sub-Total			56.176457	100	1000000	65.851256	658513
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.88531	100	1000000	3.382223	33822
Sub-Total			2.88531	100	1000000	3.382223	33822
Total			85.308102			100	1000000

Important Note
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSi or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.